

ES1A - ES1D

Features

- For surface mount applications.
- Glass passivated junction.
- Low profile package.
- · Easy pick and place.
- Built-in strain relief.
- Superfast recovery times for high efficiency.



SMA/DO-214AC COLOR BAND DENOTES CATHODE

Fast Rectifiers

Absolute Maximum Ratings* T_A = 25°C unless otherwise noted

Symbol	Parameter	Value				Units
		1A	1B	1C	1D	Office
V_{RRM}	Maximum Repetitive Reverse Voltage	50	100	150	200	V
I _{F(AV)}	Average Rectified Forward Current, @ T _A =120°C	1.0		А		
I _{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave	30		А		
T _{stg}	Storage Temperature Range	-50 to +150		°C		
T _J	Operating Junction Temperature -50 to +150		°C			

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
P _D	Power Dissipation	1.47	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient*	85	°C/W
$R_{\theta JL}$	Thermal Resistance, Junction to Lead*	35	°C/W

^{*}Device mounted on FR-4 PCB 0.013 mm.

$\textbf{Electrical Characteristics} \qquad \textbf{T}_{A} = 25 \, ^{\circ} \textbf{C unless otherwise noted}$

Symbol	Parameter		Device				Units	
			1A	1B	1C	1D		
V _F	Forward Voltage @ 1.0 A			0.9	2		V	
t _{rr}	Reverse Recovery Time $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{RR} = 0.25 \text{ A}$			15	5		ns	
I _R	Reverse Current @ rated V_R $T_A = 25^{\circ}C$ $T_A = 100^{\circ}C$		5.0 100			μΑ μΑ		
Ст	Total Capacitance V _R = 4.0 V, f = 1.0 MHz			7.0)		pF	

Typical Characteristics

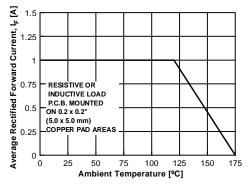


Figure 1. Forward Current Derating Curve

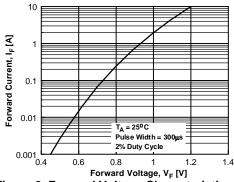


Figure 2. Forward Voltage Characteristics

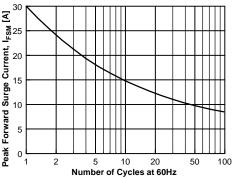


Figure 3. Non-Repetitive Surge Current

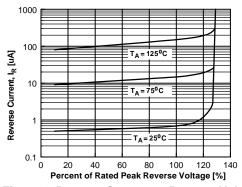
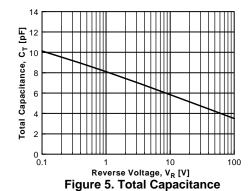
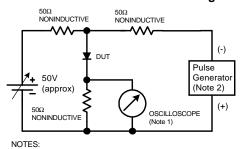
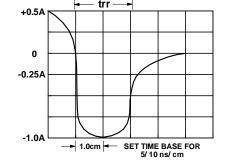


Figure 4. Reverse Current vs Reverse Voltage





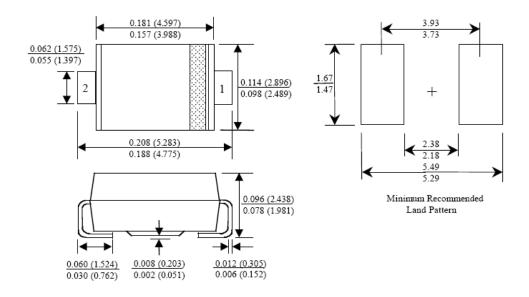
1. Rise time = 7.0 ns max; Input impedance = 1.0 megaohm 22 pf. 2. Rise time = 10 ns max; Source impedance = 50 ohms.



Reverse Recovery Time Characterstic and Test Circuit Diagram

Package Dimensions

SMA / DO - 214AC



Dimensions in Millimeters

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